# **SPECIFICATION**

<u>SPEC. No. D2013-C9</u> DATE: 2013 Sep.

To

# Non-Controlled Copy

CUSTOMER'S PRODUCT NAME

TDK'S PRODUCT NAME

Multilayer ceramic capacitors

Dipped radial lead type

FK-Series

General (Up to 50V) Mid voltage (100 to 630V)

# RECEIPT CONFIRMATION

DATE: YEAR MONTH DAY

TDK Corporation Sales

ales

Electronic Components Sales &

Marketing Group

Engineering

TDK-EPC CORPORATION

Ceramic Capacitors Business Group

TDK-MCC CORPORATION

DIELECTRIC PRODUCTS ENGINEERING DEPT.

APPROVED	Person in charge

APPROVED	CHECKED	Person in charge

### 1. SCOPE

This specification is applicable to multilayer ceramic capacitors dipped radial lead type with a priority over the other relevant specifications.

Production places defined in this specification shall be TDK Xiamen Co., Ltd. (China).

#### EXPLANATORY NOTE:

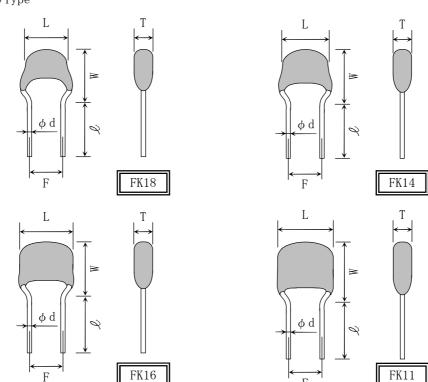
This specification warrants the quality of the lead type ceramic capacitor. The parts should be evaluated or confirmed a state of used on your product.

If the use of the parts go beyond the bounds of the specification, we can not afford to guarantee.

### 2. CODE CONSTRUCTION

(Example) FK28 X7R 1H 104 K N006
(1) (2) (3) (4) (5) (6)

(1) Type



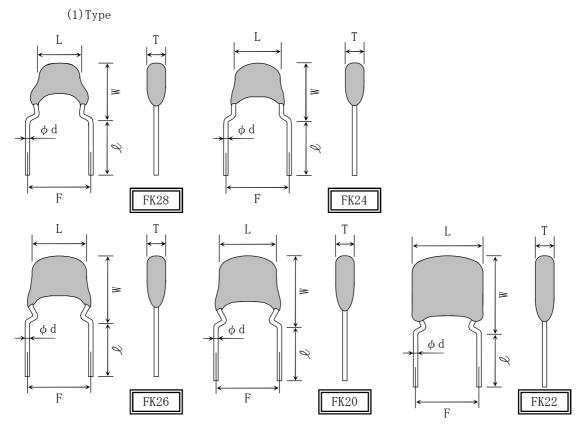
Туре	Dimensions (Unit : mm)								
	L(max.)	W(max.)	T(max.)	F	l	φd			
FK18	4.0	5. 5	2. 5						
FK14	4. 5	5. 5	2. 5	0.5100	+3.0	0.5 +0.10			
FK16	5. 5	6. 0	3. 5	$2.5 \pm 0.8$	-1.0	0.5 -0.03			
FK11	5. 5	7. 0	4. 0						

\*FK denotes forming lead.

The first digit refers to a distance between leads (  $1-2.5 \mathrm{mm}$  ), the second digit is for TDK internal code.

\*Dimension  $\mathscr L$  is applied to bulk packaging. Refer to Appendix 2 for dimension of taping packaging.





Type	Dimensions (Unit : mm)							
Type	L(max.)	W(max.)	T(max.)	F	l	φd		
FK28	4.0	5. 5	2.5					
FK24	4. 5	5. 5	2.5		7.0±2.0			
FK26	5. 5	6. 0	3. 5	$5.0\pm1.0$		$0.5 \begin{array}{c} +0.10 \\ -0.03 \end{array}$		
FK20	5. 5	7. 0	4.0					
FK22	7. 5	8. 0	4.0					

\*FK denotes forming lead.

The first digit refers to a distance between leads (  $2-5.0\mathrm{mm}$  ), the second digit is for TDK internal code.

\*Dimension  $\mathscr L$  is applied to bulk packaging. Refer to Appendix 3 for dimension of taping packaging.

(2) Temperature Characteristics (Details are shown in para 7 No. 7, 8)



(3) Rated Voltage

Symbol	Rated Voltage
Syllibo1	Kateu voitage
2 Ј	DC 630 V
2 E	DC 250 V
2 A	DC 100 V
1 H	DC 50 V
1 E	DC 25 V
1 C	DC 16 V
1 A	DC 10 V
0 Ј	DC 6.3 V

### (4) Rated Capacitance

Stated in three digits and in units of pico farads (pF). The first and second digits identify the first and second significant figures of the capacitance, the third digit identifies the multiplier.

R is designated for a decimal point.

Example

2R2 → 2.2pF

 $104 \rightarrow 100,000 \mathrm{pF}$ 

(5) Capacitance tolerance

Symbol	Tolerance	Capacitance(C)
С	±0.25 pF	C≦5pF
D	±0.5 pF	5pF <c≤10pf< td=""></c≤10pf<>
J	± 5 %	
K	±10 %	Over 10pF
M	±20 %	

(6) Internal code

Symbol	Applied voltage of Life	Packaging
N020		Bulk (FK1*type)
N000	Rated voltage ×2	Bulk (FK2*type)
N006		Ammo Pack
R020		Bulk (FK1*type)
R000	Rated voltage ×1	Bulk (FK2*type)
R006		Ammo Pack



# 3.1 Standard combination of rated capacitances and tolerances

Class	Temperature Characteristics	Capacitance (*		Rated capacitance
		C≦5	C (±0.25 pF)	1, 1.5, 2, 2.2, 3, 3.3, 4, 4.7, 5
1	000	5 <c≦10< td=""><td>D (±0.5 pF)</td><td>6, 6.8, 7, 8, 9, 10</td></c≦10<>	D (±0.5 pF)	6, 6.8, 7, 8, 9, 10
1	COG	10 <c≦10,000< td=""><td>J (± 5 %)</td><td>E-12 series</td></c≦10,000<>	J (± 5 %)	E-12 series
		10,000 < C	J (± 5 %)	E- 6 series
	X5R X7R X7S	C≦0.1	K (±10 %)	E- 6 series
2		0.1 <c≦10< td=""><td>K (±10 %)</td><td>E- 6 series</td></c≦10<>	K (±10 %)	E- 6 series
		10 < C	M (±20 %)	E- 0 Series

<sup>\*1</sup> C denotes Capacitance.

Unit : pF for Class1 and  $\mu$ F for Class2.

## 3.2 Capacitance Step in E series

E series		Capacitance Step										
E- 3	1			2.2			4. 7					
E- 6	E- 6 1 1.5		5	2. 2 3. 3			4.7 6.8			8		
E-12	1	1.2	1.5	1.8	2. 2	2. 7	3. 3	3. 9	4. 7	5. 6	6.8	8. 2

# 4. OPERATING TEMPERATURE RANGE

Т. С.	Min. operating	Max. operating	Reference		
1.0.	Temperature	Temperature	Temperature		
X5R	-55°C	85°C	25℃		
COG					
X7R	-55°C	125℃	25℃		
X7S					

#### 5. STORING CONDITION AND TERM

5 to  $40^{\circ}$ C at 20 to 70%RH

6 months Max.

### 6. INDUSTRIAL WASTE DISPOSAL

Dispose this product as industrial waste in accordance with the industrial Waste Law.



# 7. PERFORMANCE

table 1

No.	. Item		Performance	Test or inspection method			
1	External Ap	pearance	No defects which may affect performance.	By visua	l checking.		
2	Indication	Appearance	Meet a requirement per para 8.	-	1 0 1		
				solve	nt   Solvent t	emp.	Dipping time
		Resistance to solvent	Shall be visible.	Isopro alcoho		20~25 °C 30±5s.	
3	Voltage Proof	Between termination	No insulation breakdown or other damage.	for 1~5s	discharge cur	Rat Rat Rat Rat	
		Between termination coating	No insulation breakdown or other damage.		OmA. 2.5 rated volt allic small ba	ethod.)	
4			$10,000 \rm M\Omega$ or $500~\rm M\Omega$ · $\mu$ F min. (As for the capacitor of rated voltage 16,10 and 6.3V DC, $10,000~\rm M\Omega$ or $100~\rm M\Omega$ · $\mu$ F min.,) whichever smaller.	<pre>≪250V DC and under≫    Apply rated voltage. ≪630V DC≫    Apply DC500V. Applying time: 60sec.</pre>			
5	Capac	itance	Within the specified tolerance.	Class 1			
				Rated capaci 1,000p	C -	ncy	Measuring voltage
				and un Over		.0%	0.5∼5 Vrms.
				1,000p	$\frac{1 \text{kHz} \pm 1}{1}$	.0%	
				Class 2 Rated capaci 10 $\mu$ F		ncy	Measuring voltage 1.0±0.2
				and un	der 1kHz±1	.0%	Vrms. 0.5±0.2
				0ver 10 μ F	120Hz ±	10%	0.5±0.2 Vrms.
6	Q (Class 1)		As per Table 2.	See No.5 in this table for measuring condition.			measuring
	Dissipation Factor (Class 2)		T. C. D. F.  0. 03 max.  X5R 0. 05 max.  X7R 0. 075 max.  X7S 0. 10 max.  0. 15 max.	Dissipat	rmation which ion Factor, ple presentative.	_	uct has which contact with our



## (continued)

	(continue	d)			
No.		tem	Performance	Test or inspection method	
7	Temperature Characteristics of Capacitance (Class 1)		Temperature Coefficient $(ppm/^{\circ}C)$ $COG : 0 \pm 30$ Capacitance drift	Temperature Coefficient shall be calculated based on values at 25°C and 85°C temperature.  Measuring temperature below 20°C shall be -10°C and -25°C	
			Within $\pm 0.2\%$ or $\pm 0.05$ pF, whichever larger.		
8	Temperatur Characteri of Capacit (Class 2)	stics	Capacitance Change(%)  No voltage applied  X5R: ±15  X7R: ±15	Capacitance shall be measured by the steps shown in the following table, after thermal equilibrium is obtained for each step.  ΔC be calculated ref. STEP3 reading.  Step Temperature (°C)	
			X7S: ±22	Reference temp. $\pm 2$ Min. operating temp. $\pm 2$	
				$\frac{1}{3}$ Reference temp. $\pm 2$	
				4 Max. operating temp. ±2	
				As for the capacitor of rated voltage 10V DC(1A) and 6.3V DC(0J), 0.2Vrms. shall be applied.	
9	Lead Strength	Tensile Strength	No mechanical damage such as lead breakage and loosing.	With holding the parts, apply pulling force to lead drawing direction gradually. Pulling strength: 5N Holding time: 10±1s.	
		Bending Strength  No mechanical damage such as lead breakage and loosing.			
10	Vibration	External appearance	No mechanical damage.	Solder the capacitors on a P. C. Board shown in Appendix1 before testing.	
		Capacitance		Characteristics Change from the value before tes  ±2.5% or Class1 COG ±0.25pF,	
			whichever larger.   X5R	directions.	
		Q Class1 D. F. Class2	Shown in Table2.  Meet the initial spec.		

	(continued)								
No.		em	T 1 1 1		ormance		est or i		
11	Solderability		Leads shall be covered by new solder more than 75% of its surface.		Completely soak both terminations in solder at 245±5°C for 2±0.5s.  Solder: Sn-3.0Ag-0.5Cu(Pb-free) Flux: Isopropyl alcohol(JIS K 8839) Rosin(JIS K 5902) 25% solid solution.  Dipping: By 1.5~2.0mm from the root of lead.			2±0.5s. (Pb-free) 1(JIS K 8839) ) on.	
12	Resistance	External			may affect				rminations in
	to solder	appearance	performanc	е.		solder	at 250±	5°C for	$5\pm1$ s.
	heat	Capacitance	Class1	COG  X5R X7R X7S	Change from the value before test ±2.5 % or ±0.25pF whichever larger. ±7.5 % ±7.5 % ±7.5 %	Flux:	Rosin(JI 25% soli	l alcoho S K 5902 d solutio 2.0mm fro	l(JIS K 8839) )
		Q Class1	Shown in T	able2.					
		D. F. Class2	Meet the i	nitial	spec.				
		Insulation Resistance	Meet the initial spec.  No insulation breakdown or other damage.						
		Voltage proof							
13	Temperature Cycle and Dipping	Capacitance				Step	ature Cyc Temp.		Time(min.)
	Cycle	*	Character	ristics	Change from the value before test	1 2	_	b. ±3	30 ± 3  Less than 3
			Class1	COG	±2.5 % or ±0.25pF whichever larger.	3	Temp	perating b. ±3	30 ± 3
			101 0	X5R	± 7.5 %	4	Reference	ce temp.	Less than 3
			*Class2 $\begin{vmatrix} X7R \\ X7S \end{vmatrix} = \frac{1.5 \%}{\pm 10 \%}$		Dipping	c Cvcle			
			*Applied		ome parts	Step	Temp. (°C)	Time (min.)	Solidy liquid
		Q Class1	Shown in T	able2.		1	65 <sup>+5</sup> 0	15±2	Pure water
		D. F Class2	Meet the i	nitial	spec.	2	0±3	15±2	Saturation salt water
		Insulation Resistance	Meet the i	nitial	spec.				n a P.C.Board re testing.
		Voltage proof	No insulat damage.	ion bre	eakdown or other				ambient ng time before
						Class Class		±2h ±4h	
									e(5 cycle) and consecutively.



	(continued)					
No.	Ite	em	P	erfo	ormance	Test or inspection method
14	Moisture Resistance (Steady State)	External appearance Capacitance	shown in Appendix1 befor			Solder the capacitors on a P.C.Board shown in Appendix1 before testing.  Leave at temperature $40\pm2^{\circ}\text{C}$ , 90 to
	(Steady States)	Capacitance	Characterist	ics	Change from the value before test	95%RH for 500 +24,0h. Leave the capacitors in ambient
			Class1 CO	ЭG	$\pm$ 5% or 0.5pF whichever larger.	condition for the following time before measurement. Class1 : 24±2h
			*Class2 X7	5R 7R 7S	±12.5% ±25 %	Class2 : 48±4h
			*Applied fo	or s	ome parts	
		Q Class1	Shown in Tabl			
		D. F. Class2	Characteristi 200% of init		spec max.	
		Insulation Resistance	voltage 16,10	apa an 10	citor of rated d 6.3V DC, MΩ•μF min.,)	
15	Moisture Resistance	External appearance Capacitance	No mechanical	daı	mage.	Solder the capacitors on a P.C.Board shown in Appendix1 before testing.  Apply the rated voltage at temperature
		Capacitance	Characterist	ics	Change from the value before test	$40\pm2$ °C and 90 to 95%RH for 500 +24,0h.
			Class1 CO	OG .	$\pm 7.5\%$ or $\pm 0.75$ pF whichever larger.	Charge/discharge current shall not exceed 50mA.  Leave the capacitors in ambient
				5R 7R 7S	±12.5 % ±25 %	condition for the following time before measurement. Class1 : 24±2h
			*Applied fo		ome parts	Class2 : 48±4h Voltage conditioning : (Only Class2)
		Q Class1	Shown in Tabl			Voltage treat the capacitor under testing temperature and voltage for lhour.
		D. F. Class2	Characteristi 200% of initi		spec max.	Leave the capacitors in ambient condition for 48 ± 4h before
		Insulation Resistance	$500 M \Omega$ or $25 M$ (As for the convoltage 16,10 $500 M \Omega$ or $5 M$ whichever small	apa ) an (Ω•	citor of rated d 6.3V DC, $\mu$ F min.,)	measurement. Use this measurement for initial value.

### (continued)

No.	I	tem		Perfo	ormance	Test or inspection method
16	Life	External appearance Capacitance	No mechanical damage.			Solder the capacitors on a P.C.Board shown in Appendix1 before testing.
		capacitance	Character	ristics	Change from the value before test	Below the voltage shall be applied at maximum operating temperature $\pm 2^{\circ}\mathrm{C}$ for
			Class1	COG	$\pm 3\%$ or $\pm 0.3\%$ whichever larger.	1,000 +48,0h.  Applied voltage
			*Class2	X5R X7R	±15 %	Rated voltage ×2
				X7S	±25 %	Rated voltage ×1
					ome parts	For information which products has
		Q Class1	Shown in Ta	able2.		which applied voltage, please contact with our sales representative.
		D.F. Class2	characteri 200% of in		spec max.	Charge/discharge current shall not exceed 50mA.
		Insulation Resistance	voltage 16	e capad ,10 and or 10M	eitor of rated d 6.3V DC, $\Omega$ • $\mu$ F min.,)	Leave the capacitors in ambient condition for the following time before measurement.  Class1 : 24±2h Class2 : 48±4h  Voltage conditioning : (Only Class2) Voltage treat the capacitor under testing temperature and voltage for 1hour.  Leave the capacitors in ambient condition for 48±4h before measurement.  Use this measurement for initial value.

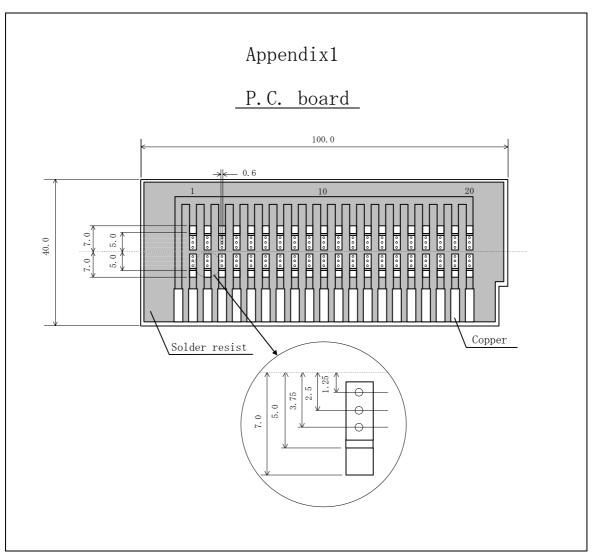
<sup>\*</sup> As for the initial measurement of capacitors (Class2) on number 8, 10, 12, 13, and 14, leave capacitors at 150 -10,0°C for 1h and measure the value after leaving capacitors for  $48\pm4h$  in ambient condition.

#### table2

Specifi	ication	Applicable numbers of Table1
30pF and over Less than 30pF	$Q \ge 1,000$ $Q \ge 400+20 \cdot C$	6, 10, 12, 13
30pF and over Less than 30pF	$Q \ge 350$ $Q \ge 275 + 5/2 \cdot C$	14, 16
30pF and over Less than 30pF	$Q \ge 200$ $Q \ge 100+10/3 \cdot C$	15

(Note) : C denotes Rated Capacitance(pF)





(Unit:mm)

1. Material :Glass Epoxy (As per JIS C6484 GE4)

2. Thickness: 1.6mm Copper(Thickness: 0.035mm)

Solder resist



# 8. INDICATION

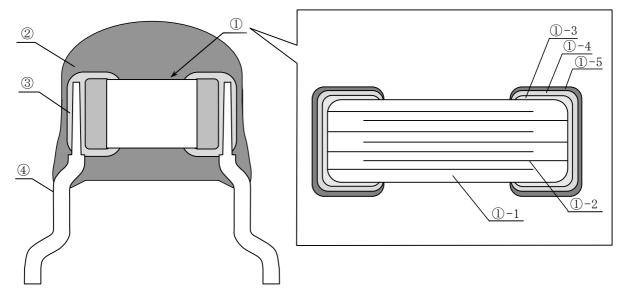
## 8.1 Indication (Example)

Type T. C.	FK18 FK14 FK28 FK24	FK16 FK11 FK26 FK20	F K 2 2
C 0 G	(2)— 102	(1) $(2)$ $(4)$ $(3)$ $(3)$	$ \begin{array}{c c} (1) & & \\ (2) - & & \\ (4) - & & TDK \end{array} $ $ \begin{array}{c} (3) - \\ (5) \end{array} $
X 5 R X 7 R X 7 S	(2)— 103	(2)— $(4)$ — $(3)$	$ \begin{array}{c} (2) - \\ (4) - \\ \hline                                  $

## 8.2 Meaning of indication

		Туре				
Item	Detail	FK18, FK14 FK28, FK24	FK16, FK11, FK26, FK20	FK22		
(1) T. C.	For COG, indicate Black mark on the head.		0	0		
(2) Rated Capacitance	Indicate in three digits.	0	0	0		
(3) Capacitance tolerance	Indicates the symbol.		0	0		
(4) Rated voltage	For DC50V, indicate a bar under the rated capacitance.		0	0		
(5) Manufacturer	Indicates "TDK".			0		

### 9. INSIDE STRUCTURE AND MATERIAL



Mo	No. NAME		NAME	MATERIAL		
INO.			NAME	Class 1	Class 2	
		1 -1	Dielectric	${\tt CaZr0_3}$	${\tt BaTiO_3}$	
	Multilayer ①-2		Electrode	Ni		
1	Ceramic Chip	①-3		Cu		
	Capacitors	1)-4	Termination	Ni		
		①-5		S	n	
2	C	Coating		Ерс	ОХУ	
3	Solder for joint		High temp	o. solder		
4	Le	ad wir	`e	Solder coated	l copper wire	

### 10. PACKAGING

Packaging shall be done to protect the components from the damage during Transportation and storing, and a label which has the following information shall be attached.

- 1) Total number of components in a plastic bag: 500pcs.max.
- 2) Tape packaging is as per TDK tape packaging specification.
  - 1) Inspection No. \*
  - 2) TDK P/N
  - 3) Customer's P/N
  - 4) Quantity
  - \* Composition of Inspection No.

Example 
$$\frac{X}{(a)} \frac{3}{(b)} \frac{A}{(c)} - \frac{\bigcirc\bigcirc}{(d)} - \frac{\bigcirc\bigcirc\bigcirc}{(e)}$$

- a) Line code
- b) Last digit of year
- c) Month and A for January and B for February and so on. (Skip I)
- d) Inspection Date of the month.
- e) Serial No. of the day



# 11. Caution

11.	Caution	
No.	Process	Condition
1	Operating Condition (Storage, Transportation)	1-1. Storage  1) The capacitor must be stored in an ambient temperature of 5~40°C with a relative humidity of 20~70%. The products should be used within 6 months upon receipt.
	114.10 p. 2. 144.141.	2) The capacitors must be operated and stored in an environment free of dew condensation and these gases such as Hydrogen Sulphide, Hydrogen Sulphate, Chlorine, Ammonia and sulfur.
		3) Avoid storing in sun light and wet with dew.
		4) Do not use capacitors under high humidity and high and low atmospheric pressure which may affect capacitors reliability.
		5) Capacitors should be tested for the solderability when they are stored for long time.
		1-2. Handling in transportation  1) In case of the transportation of the capacitors, the performance of the capacitors may be deteriorated depending on the transportation condition.  (Refer to JEITA RCR-2335B 9.2 Handling in transportation)
2	Circuit design  Caution	2-1. Operating temperature Operating temperature should be followed strictly within this specification, especially be careful with the maximum temperature.
		1) Do not use capacitor above the maximum allowable operating temperature.
		2) Surface temperature including self heating should be below maximum operating temperature.  (Due to dielectric loss, capacitor will heat itself when AC is applied. Especially at high frequencies around its SRF, the heat might be so extreme that it may damage itself or the product mounted on. Please design the circuit so that the maximum temperature of the capacitor including the self heating to be below the maximum allowable operating temperature.  Temperature rise shall be bellow 20°C.)
		3) The electrical characteristics of the capacitors will vary depending on the temperature. The capacitors should be selected and designed in taking the temperature into consideration.
		2-2. Operating voltage  1) Operating voltage across the terminals should be below the rated voltage.  When AC and DC are super imposed, VO-P must be below the rated voltage.  ———————————————————————————————————
		AC or pulse with overshooting, $V_{P-P}$ must be below the rated voltage. ———(3), (4) and (5)
		When the voltage is started to apply to the circuit or it is stopped applying, the irregular voltage may be generated for a transit period because of resonance or switching. Be sure to use a capacitor within rated voltage containing these irregular voltage.

No.	Process	Condition
2	Circuit design	
	⚠ Caution	Voltage (1) DC voltage (2) DC+AC voltage (3) AC voltage
		Positional Measurement (Rated voltage) $V_{0-P}$ $0$ $V_{P-P}$ $0$
		Voltage (4) Pulse voltage (A) (5) Pulse voltage (B)
		Positional Measurement (Rated voltage)
		2) Even below the rated voltage, if repetitive high frequancy AC or pulse is applied, the reliability of the capacitor may be reduced.
		3) The effective capacitance will vary depending on applied DC and AC voltages.  The capacitors should be selected and designed in taking the voltages into consideration.
		2-3. Frequency 1) When the capacitors (Class 2) are used in AC and/or pulse voltages, the capacitors may vibrate themselves and generate audible sound.
3	Designing P.C.board	If capacitor leads are inserted into different pitch holes, it may induce excessive stress in the capacitor or outer resin to result in cracking, and it may degrade the quality.  Recommend capacitor layout is as following.
		Not recommended Recommend

No.	Process	Condition
4	Lead wire insertion	1) If the leads clinching is too tight, the lead wire tend to be pulled excessively to cause lead wire breakage or cracking of the coating and quality degradation. Please adjust the clinching and provide sufficient preventive maintenance. Recommended capacitor layout is as following.
		Not recommended Recommended
		Clinching
		2) If capacitor leads are inserted into different pitch holes, it may induce excessive stress in the capacitor or outer resin to result in cracking, and it may degrade the quality.  When the lead pitch does not fit with the through hole on the pc board, please adjust the lead pitch so that the capacitor body would not receive excessive force.
5	Soldering	<ul> <li>5-1. Flux selection     Although highly-activated flux gives better solderability, substances which increase activity may also degrade the insulation of the capacitors. To avoid such degradation, it is recommended following.</li> <li>1) It is recommended to use a mildly activated rosin flux (less than 0.1wt% chlorine). Do not use acidic flux is not recommended.</li> <li>2) Excessive flux must be avoided. Please provide proper amount of flux.</li> <li>3) When water-soluble flux is used, enough washing is necessary.</li> <li>5-2. Recommended soldering profile by various methods     Flow soldering     Soldering     Natural cooling     Annual soldering     Solder iron)     Avoiding thermal shock     Preheating condition     Soldering     Temp. (*C)     Wave soldering     AT≦150     Manual soldering     AT≦150     Manual soldering     AT≦190</li> </ul>

No.	Process	Condition
5	Soldering	2) Cooling condition  Natural cooling using air is recommended. If the chips are dipped into a solvent for cleaning, the temperature difference (ΔT) must be less than 100°C.
		5-4. Amount of solder In sufficient solder may detach the capacitor from the P.C. board. See bellow for example of solder amount.
		Adequate
		Insufficient contact failure or capacitor comes off the P.C. board.
		5-5. Solder repair by solder iron Tip temperature of solder iron varies by its type, P.C. board material and solder land size. Higher the tip temperature, quick the operation is, but the heat shock may crack the capacitor. Following condition is recommended.
		( Recommended solder iron condition ) Temp. (°C) Wattage (W) Shape (mm) Time (sec.)
		Temp. (°C)         Wattage (W)         Shape (mm)         Time (sec.)           350 MAX.         20 MAX.         φ 3.0 MAX.         3 MAX.
6	Cleaning	<ol> <li>If an unsuitable cleaning fluid is used, flux residue or some foreign articles may stick to capacitor surface to deteriorate especially the insulation resistance.</li> <li>If cleaning condition is not suitable, it may damage the capacitor.</li> <li>Insufficient washing         <ul> <li>Terminal electrodes may corrode by Halogen in the flux.</li> <li>Halogen in the flux may adhere on the surface of capacitor, and lower the insulation resistance.</li> <li>Water soluble flux has higher tendency to have above mentioned problems (1) and (2).</li> </ul> </li> <li>Excessive washing         <ul> <li>Excessive washing way damage the coating material of coated capacitor and deteriorate it.</li> </ul> </li> </ol>
		(2) When ultrasonic cleaning is used, excessively high ultrasonic energy output can affect the adhesion between the ceramic dielectric and the terminal electrodes.  To avoid this, following is the recommended condition.
		Power : 20W/L max. Frequency : 40kHz max. Washing time : 5 minutes max.
		2)-3. If the cleaning fluid is contaminated, density of Halogen increases, and it may bring the same result as insufficient cleaning.

No.	Process	Condition
7	Coating and molding of the P.C.board	1) When the P.C. board is coated, please verify the quality influence on the product.
		2) Please verify carefully that there is no harmful decomposing or reaction gas emission during curing which may damage the capacitor.
		3) Please verify the curing temperature.
8	Lead wire bending	During lead wire bending process, mechanical stress often concentrates in one part of capacitor body and it may damage the ceramic and the coating.  Refer to following for bending the lead wire.
		fixture
		When bending the lead wire, hold the wire closer to the capacitor with a fixture so that the lead bending would not affect the capacitor body.
9	Handling of loose capacitor	If dropped the capacitor may crack. Once dropped do not use it. Especially, the large case sized capacitor is tendency to have cracks easily, so please handle with care.
		crack
10	Capacitance aging	The capacitors (Class 2) have aging in the capacitance. They may not be used in precision time constant circuit. In case of the time constant circuit, the evaluation should be done well.

No.	Process	Condition
11	Estimated life and estimated failure rate of capacitors	The estimated life and the estimated failure rate depend on the temperature and the voltage. This can be calculated by the equation described in JEITA RCR-2335B Annex F(Informative) Calculation of the estimated lifetime and the estimated failure rate (Temperature acceleration: 3rd powered low, Voltage acceleration: 10degC law) The failure rate can be decreased by reducing the temperature and the voltage but they will not be guaranteed.
12	Others A Caution	The products listed on this specification sheet are intended for use in general electronic equipment (AV equipment, telecommunications equipment, home appliances, amusement equipment, computer equipment, personal equipment, office equipment, measurement equipment, industrial robots) under a normal operation and use condition.  The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below or for any other use exceeding the range or conditions set forth in this specification sheet.  Aerospace/Aviation equipment. Transportation equipment (cars, electric trains, ships, etc.) Medical equipment. Power-generation control equipment. Atomic energy-related equipment. Seabed equipment. Transportation control equipment. Public information-processing equipment. Military equipment. Electric heating apparatus, burning equipment. Disaster prevention/crime prevention equipment. Safety equipment. Other applications that are not considered general-purpose applications.  When using this product in general-purpose applications, you are kindly requested to take into consideration securing protection circuit/equipment or providing backup circuits, etc., to ensure higher safety.



# TAPE PACKAGING SPECIFICATION



### 1. CONSTRUCTION AND DIMENSION OF TAPING

Dimensions of FK1\* type shall be according to Appendix 2. Dimensions of FK2\* type shall be according to Appendix 3.

### 2. QUANTITY

Туре	Parts quantity/box (pcs.)
FK18, FK28 FK14, FK24 FK16, FK26	2, 000
FK11, FK20 FK22	1, 500

### 3. PERFORMANCE SPECIFICATIONS

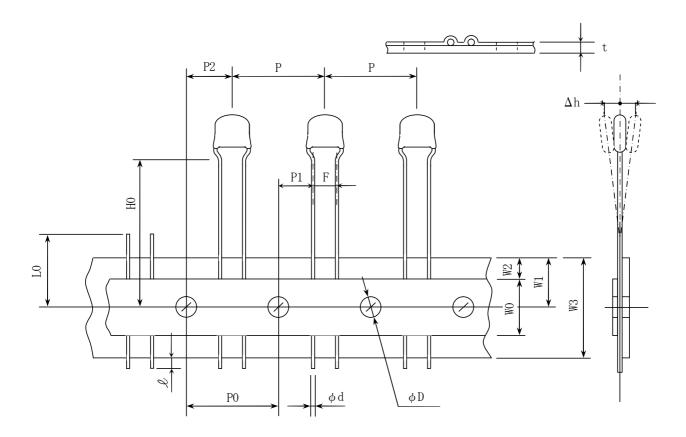
- 3-1. The missing of components shall be within consecutive 3pcs.
- 3-2. Empty part for min 3pcs shall be provided at the beginning and the end of taping.
- 3-3. Shipping label must be attached at the side of carton.
- 3-4. When pull the carrier tape for left side with keeping the head of capacitors to the direction of the above figure, adhesive tape shall be upper side.
- 3-5. Folded tape shall contain 25pcs. of components.



— 20 ——

# Taping dimensions

(FK18, FK14, FK16, FK11)



(Unit:mm)

		(CITIC: HIII)
Symbol Symbol	Dimensions	Tolerance
Р	12. 7	±1. 0
P 0 ※1	12. 7	±0.3
P 1	5. 1	±0.7
P 2	6.35	±1. 3
WO	12.0	±1. 0
W 1	9. 0	±0.5
W2 <b>%</b> 2	3. 0	3. O and under
W3	18.0	+1.0, -0.5
H0	16.0	±0.5
l	1. 0	1. O and under
t	0. 6	±0.2
L 0	11.0	11. O and under
F	2. 5	+0.5, -0.2
φd	φ0. 5	+0.1, -0.03
φD	φ4. 0	±0.2
$\Delta$ h		± 2

31 Accumulated pitch tolerance shall be  $\pm 2$ mm for 20 pitches.

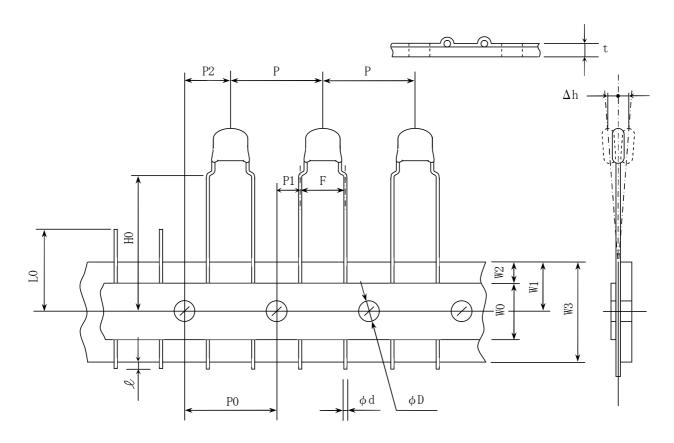
 $\slash\hspace{-0.8em}\cancel{\times}\hspace{-0.8em}2$  Adhesive tape shall not stick out from carrier tape.



# Appendix 3

# Taping dimensions

(FK28, FK24, FK26, FK20, FK22)



(Unit:mm)

		(CITT C . Hall)
Symbol	Dimensions	Tolerance
P	12. 7	±1. 0
P 0 <b>%</b> 1	12. 7	±0.3
P 1	3.85	±0.7
P 2	6.35	±1. 3
W0	12.0	±1. 0
W 1	9. 0	±0.5
W2 <b>%</b> 2	3. 0	3. O and under
W3	18.0	+1.0, -0.5
Н0	16.0	±0.5
l	1. 0	1. O and under
t	0. 6	±0.2
L 0	11. 0	11. O and under
F	5. 0	+0.8, -0.2
φd	φ0. 5	+0.1, -0.03
φD	φ4. 0	±0.2
$\Delta$ h		± 2

31 Accumulated pitch tolerance shall be  $\pm 2$ mm for 20 pitches.

 $\slash\hspace{-0.8em}\cancel{\times}\hspace{-0.8em}2$  Adhesive tape shall not stick out from carrier tape.



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